

## **3M Joins the US-JOINT Consortium for Next-Generation Semiconductor Packaging**

Tokyo – February 4, 2025 – Resonac Corporation (President: Hidehito Takahashi, hereinafter referred to as "Resonac"), which took the lead in the establishment of the US-JOINT consortium\*<sup>1</sup> for next-generation semiconductor packaging, is pleased to announce that 3M Company (ST. PAUL, Minn. USA, hereinafter referred to as "3M") has newly joined the consortium. With this addition, US-JOINT now comprises 12 companies from Japan and the United States.

"As the demands of AI and other high performance computing technologies increase, suppliers must work together to provide comprehensive solutions to tough challenges on increasingly shorter timelines." said Steven Vander Louw, 3M's president of display and electronics product platforms. "The companies in the US-JOINT Consortium represent US and Japanese innovation leaders in a range of advanced packaging technologies. 3M is pleased to join the consortium in order to bring our decades of materials science expertise, across more than 50 technology platforms, to help address these challenges."

By adopting 3M's materials science technologies, US-JOINT consortium's research and development on next-generation semiconductor packaging will be further accelerated.

"We are delighted to welcome 3M to the US-JOINT Consortium," said Hidenori Abe, Corporate Officer, CTO for semiconductor materials, Resonac. "3M's expertise in materials science and commitment to innovation in advanced packaging device and process solutions will be an asset as we work together to solve difficult technical and integration challenges for customers onshore in the United States."

Next-generation semiconductors, particularly those aimed at the rapidly growing AI market, are achieving enhanced performance through cutting-edge packaging technologies such as 2.5D and 3D\*<sup>2</sup>. In recent years, not only semiconductor manufacturers but also major tech companies, including hyperscalers and fabless companies, have been creating the latest concepts in semiconductor packaging. US-JOINT will collaborate with these companies to validate the latest concepts in semiconductor packaging. US-JOINT plans to establish a research and development center equipped with clean rooms and manufacturing equipment in Silicon Valley, and commence operating it by the end of 2025.

Moving forward, Resonac will continue conducting research and development on cutting-edge packaging technologies that support the evolution of semiconductors in collaboration with US-JOINT.

For details, please refer to the website, Resonac Holdings Corporation:  
<https://www.resonac.com/>.



\*1. News release regarding the establishment of US-JOINT:

<https://www.resonac.com/news/2024/07/08/3116.html>

\*2. 2.5D packaging is a technology to place semiconductor chips in parallel on the silicon substrate, which is called "interposer." 3D packaging is a technology to stack chips.

### About the Resonac Group

The Resonac Group was established in January 2023 as a result of the integration of the Showa Denko Group and the Showa Denko Materials Group (former Hitachi Chemical Group). The Group's annual sales of semiconductor and electronic materials amount to approximately 340 billion yen. The Group is recognized for its extensive lineup of semiconductor materials for back-end processes, which have top market share globally. The integration of the two companies has enabled the Resonac Group to make material design and development in-house from raw materials through to finished goods. The new trade name "RESONAC" was created as a combination of two English words, namely, the word "RESONATE" and "C" from the first letter of CHEMISTRY. The Resonac Group actively leverages its co-creative platform to accelerate technological innovation with semiconductor manufacturers, materials manufacturers, and equipment manufacturers in Japan and across the globe.

### About 3M

3M believes science helps create a brighter world for everyone. By unlocking the power of people, ideas and science to reimagine what's possible, our global team uniquely addresses the opportunities and challenges of our customers, communities, and planet. Learn how we're working to improve lives and make what's next at [3M.com/news](https://www.3m.com/news).

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